



Product Change Notification / JAON-14MTDX268

Date:

13-Jan-2021

Product Category:

8-bit Microcontrollers, Capacitive Touch Sensors, Touchscreen Controllers

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4492 Initial Notice: Qualification of NSEB as a new assembly site for selected Atmel products available in 28L VQFN (4X4X1mm) package with MSL 1 classification.

Affected CPNs:

[JAON-14MTDX268_Affected_CPN_01132021.pdf](#)

[JAON-14MTDX268_Affected_CPN_01132021.csv](#)

Notification Text:

PCN Status: Initial notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change: Qualification of NSEB as a new assembly site for selected Atmel products available in 28L VQFN (4X4X1mm) package with MSL 1 classification.

Pre Change:

Assembled at ASKR assembly site using palladium coated copper (PdCu) bond wire or gold (Au) bond wire, EN-4900GC die attach material, with PPF or Matte Sn lead plating finish, Ring plating DAP Surface Prep, without lead-lock lead frame and MSL 1 / MSL 3 classification.

Post Change:

Assembled at NSEB assembly site using palladium coated copper with gold flash (CuPdAu) bond wire, 8600 die attach material with Matte Sn lead plating finish, Ag on lead only DAP Surface Prep and with lead-lock lead frame and MSL 1 classification.

Pre and Post Change Summary:

	Pre Change		Post Change
Assembly Site	ASE Korea Inc. (ASKR)		UTAC Thai Limited (NSEB)
Wire material	PdCu	Au	CuPdAu
Die attach material	EN-4900GC		8600
Molding compound material	G700		G700
Lead frame material	C194		C194
Lead Frame Lead Lock	No		Yes
Lead Plating Finish	Matte Sn	PPF	Matte Sn
Lead Frame DAP Surface Prep	Ring plating		Ag on lead only
MSL Classification	MSL 1	MSL 3	MSL 1

Impacts to Data Sheet: None

Change Impact:None

Reason for Change:To improve productivity by qualifying NSEB as a new assembly site.

Change Implementation Status:In Progress

Estimated Qualification Completion Date:July 2021

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	January 2021					-->	July 2021				
Workweek	01	02	03	04	05		27	28	29	30	31
Initial PCN Issue Date			X								
Qual Report Availability											X
Final PCN Issue Date											X

Method to Identify Change: Traceability code

Qualification Plan:Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: January 13, 2021: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_JAON-14MTDX268_Qual_Plan.pdf](#)

[PCN_JAON-14MTDX268_Pre and Post Change_Summary.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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